Electronic Paten	t App	lication Fee	Transmit	tal:			
Application Number:	107	10773968					
Filing Date:	06-	06-Feb-2004					
Title of Invention:	Dev	Device and method for forming improved resist layer					
First Named Inventor/Applicant Name:	Pau	Paul D. Shirley					
Filer:	Joh	John Reed/karen ochsenbein					
Attorney Docket Number:	MIC	MIO 0112 PA/40509.272					
Filed as Large Entity							
Utility under 35 USC 111(a) Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:			· · · · · ·				
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			540